



SMTA China South 华南高科技会议 Technical Conference

30th August 2016 (Tuesday) / 2016 年 8 月 30 日(星期二)

(CS16-TC1) Technology Conference / 高科技技术研讨会

Conference Chairman/会议主席:

Dong Lin 董林

Member of SMTA China Technical Advisory Committee / 中国 SMTA 技术顾问委员会委员

Section Manager, SMT Engineering of Artesyn Embedded Technologies

雅特生科技表面贴装工程分部经理

Venue/地点	Room No.314, 3/F, Shenzhen Convention & Exhibition Center, Shenzhen, China 中国深圳会展中心三楼 314 会议室	
Time/时间	Topic/议题	Speaker/主讲人
10:30 – 11:05	The Challenge and Solution for Rework of Array Components 阵列式元器件维修的挑战与解决方案 (CS16-TC1.1)	Robin Hou 侯砚龙 IBM Procurement China Limited 国际商业机器采购(中国)有限公司
11:05 – 11:40	Package Warpage Control and SMT Solder Joint Defects 封装曲扭变形的控制与表面贴装焊点缺陷 (CS16-TC1.2)	Dr. Wayne Koh 葛唯恩博士 Pacrim Technology Inc. 美国加利福尼亚州环太科技公司
11:40 – 12:15	Why Clean A No-Clean Flux 为何需要清洗免洗助焊剂 (CS16-TC1.3)	Jason Chan 詹益泓 Kyzen Corporation 美国 Kyzen 公司
12:15 – 13:45	Lunch Break / 午餐	
13:45 – 14:20	The Physical and Chemical Attribute Study of No Clean Flux Residues and Reliability Risk Assessment of Its Impact To Corrosions On PCBA of Electronic Products 关于免清洗助焊剂残留物的物理化学属性的研究以及对 PCBA 电子产品的腐蚀和可靠性风险的评估 (CS16-TC1.4)	Henley Zhou 周辉 Flex 伟创力
14:20 - 14:55	Solderability and Reliability Evolution of No-Clean Solder Fluxes for Selective Soldering 选择性焊接用助焊剂的可焊性和可靠性发展趋势 (CS16-TC1.5)	Luke Chen 陈卫健 Inventec Performance Chemicals(Shanghai) Co., Ltd. 欧纷泰化工(上海)有限公司

All papers will be presented in Chinese 所有演讲者都将使用中文



SMTA China South 华南高科技会议 Technical Conference

31th August 2016 (Wednesday) / 2016 年 8 月 31 日(星期三)

(CS16-TC2) Technology Conference / 高科技技术研讨会

Conference Chairman/会议主席:

Henley Zhou 周辉

Member of SMTA China Technical Advisory Committee / 中国 SMTA 技术顾问委员会委员

Director of Advanced Manufacturing Engineering, Asia of Flex

伟创力亚洲区先进制造工程部总监

Venue/地点	Room No.314, 3/F, Shenzhen Convention & Exhibition Center, Shenzhen, China 中国深圳会展中心三楼 314 会议室	
Time/时间	Topic/议题	Speaker/主讲人
10:30 – 11:05	Thermal and Mechanical Reliability of Low-Temperature Solder Alloys for Handheld Devices 应用于手持设备装配的低温焊料合金的热循环和机械可靠性 (CS16-TC2.1)	Andy Yuen 阮金全 Alpha Assembly Solutions 爱法组装材料
11:05 – 11:40	Fluid Flow Mechanics: Key To Low Standoff Cleaning 低间隙清洗工艺中的流体力学研究 (CS16-TC2.2)	Jimmy Tian 田剑 ZESTRON Asia North ZESTRON 北亚分公司
11:40 – 12:15	Design Improvements for Selective Soldering Assemblies 选择性焊接组件的设计改进 (CS16-TC2.3)	Khoh Kar Heong 许教雄 Vitronics Soltec Corp 维多利绍德公司
12:15 – 13:45	Lunch Break / 午餐	
13:45 – 14:20	High Reliability Interconnects for High Power LED Assembly 大功率LED组装的高可靠性连接解决方案 (CS16-TC2.4)	Jackson Chan 陈嘉贤 Alpha Assembly Solutions 爱法组装材料
14:20 - 14:55	The Failure Analysis and Improvement Solution for Typical Defect From Eye of Needle Press Fit Process 鱼眼针脚压接制程的典型不良分析与改善方案 (CS16-TC2.5)	Henley Zhou 周辉 Flex 伟创力
14:55 - 15:30	Readability of Directly-Marked Traceability Symbols On PCBs 印刷电路板上追溯符号的可读性 (CS16-TC2.6)	Christoph Wimmer 克里斯托夫·温默 Microscan 美国迈思肯

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